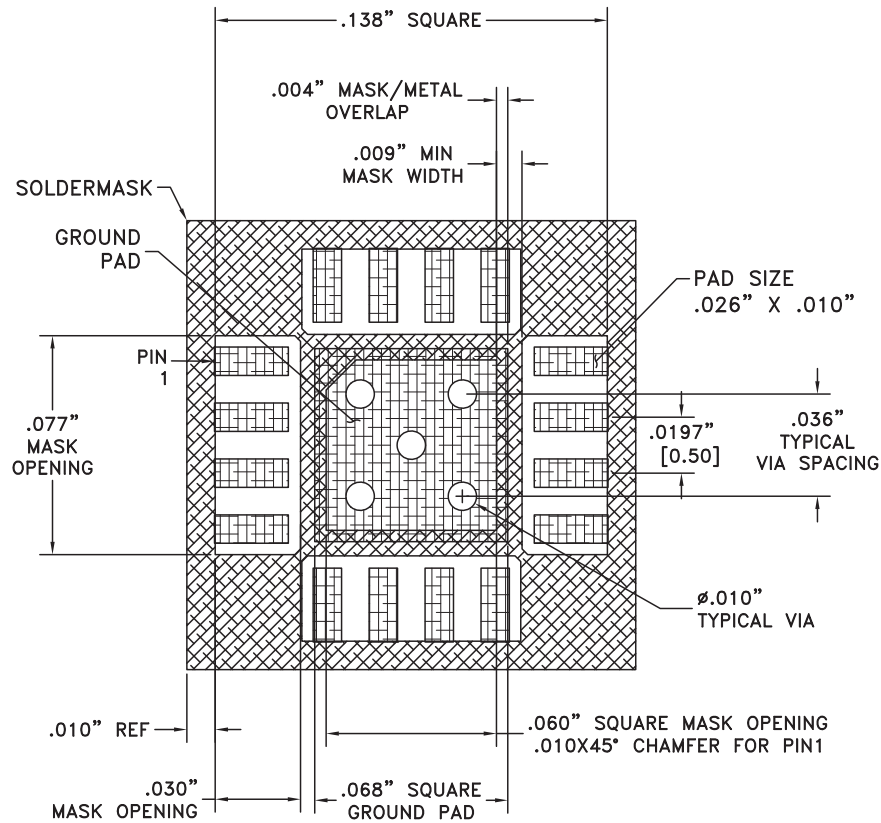


**LC3 – 3 x 3 mm QFN CERAMIC
HIGH FREQUENCY SMT PACKAGE**

Suggested LC3 PCB Land Pattern



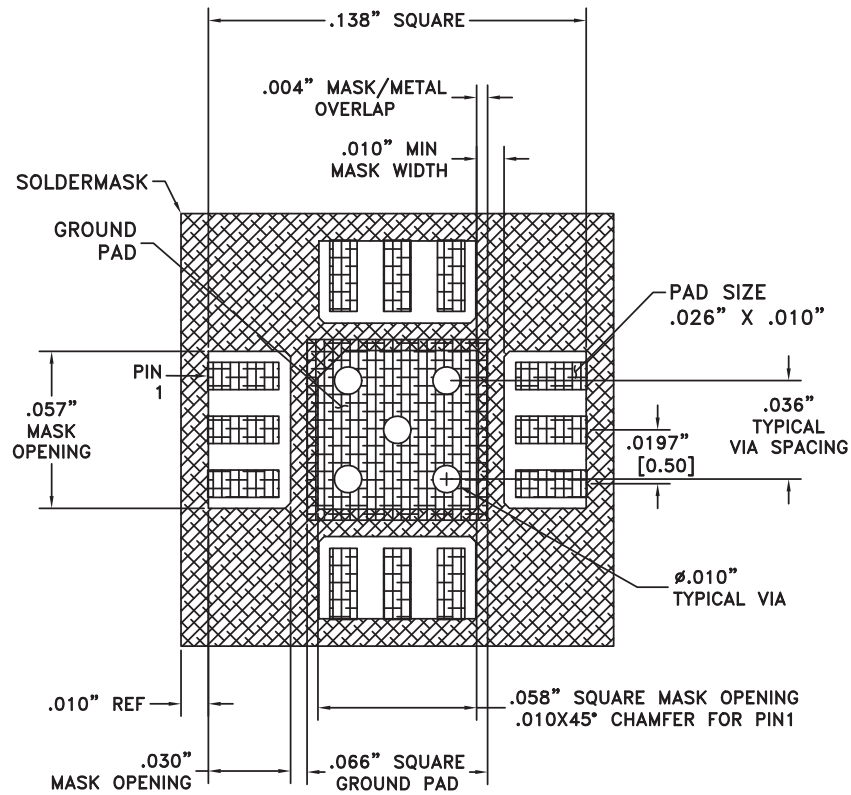
NOTES:

1. DIMENSIONS ARE IN INCHES [MILLIMETERS].
2. PAD WIDTH SHOWN IS FOR SOLDERING ONLY. BEYOND SOLDERING AREA ALL CONDUCTORS THAT CARRY RF AND MICROWAVE SIGNALS SHOULD HAVE 50 OHM CHARACTERISTIC IMPEDANCE.



**LC3B – 3 x 3 mm QFN CERAMIC
HIGH FREQUENCY SMT PACKAGE**

Suggested LC3B PCB Land Pattern



NOTES:

1. DIMENSIONS ARE IN INCHES [MILLIMETERS].
2. PAD WIDTH SHOWN IS FOR SOLDERING ONLY. BEYOND SOLDERING AREA ALL CONDUCTORS THAT CARRY RF AND MICROWAVE SIGNALS SHOULD HAVE 50 OHM CHARACTERISTIC IMPEDANCE.

